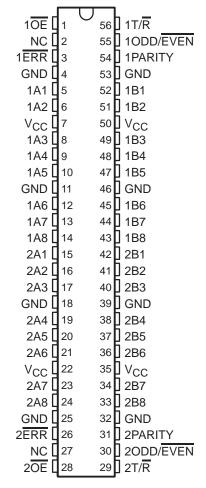
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- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V<sub>OLP</sub> (Output Ground Bounce) < 1 V at  $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OI</sub>)
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

### description

The 'ABT16657 contain two noninverting octal transceiver sections with separate parity generator/checker circuits and control signals. For either section, the transmit/receive  $(1T/\overline{R})$  or  $2T/\overline{R}$ ) input determines the direction of data flow. When  $1T/\overline{R}$  (or  $2T/\overline{R}$ ) is high, data flows from the 1A (or 2A) port to the 1B (or 2B) port (transmit mode); when  $1T/\overline{R}$  (or  $2T/\overline{R}$ ) is low, data flows from the 1B (or 2B) port to the 1A (or 2A) port (receive mode). When the output-enable (10E or  $2\overline{OE}$ ) input is high, both the 1A (or 2A) and 1B (or 2B) ports are in the high-impedance state.

SN54ABT16657 . . . WD PACKAGE SN74ABT16657 . . . DGG OR DL PACKAGE (TOP VIEW)



NC - No internal connection

Odd or even parity is selected by a logic high or low level, respectively, on the 1ODD/EVEN (or 2ODD/EVEN) input. 1PARITY (or 2PARITY) carries the parity bit value; it is an output from the parity generator/checker in the transmit mode and an input to the parity generator/checker in the receive mode.

In the transmit mode, after the 1A (or 2A) bus is polled to determine the number of high bits, 1PARITY (or 2PARITY) is set to the logic level that maintains the parity sense selected by the level at the 1ODD/EVEN (or 2ODD/EVEN) input. For example, if 1ODD/EVEN is low (even parity selected) and there are five high bits on the 1A bus, then 1PARITY is set to the logic high level so that an even number of the nine total bits (eight 1A-bus bits plus parity bit) are high.



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SCBS103B - FEBRUARY 1992 - REVISED JANUARY 1997

### description (continued)

In the receive mode, after the 1B (or 2B) bus is polled to determine the number of high bits, the  $1\overline{ERR}$  (or  $2\overline{ERR}$ ) output logic level indicates whether or not the data to be received exhibits the correct parity sense. For example, if  $10DD/\overline{EVEN}$  is high (odd parity selected), 1PARITY is high, and there are three high bits on the 1B bus, then  $1\overline{ERR}$  is low, indicating a parity error.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

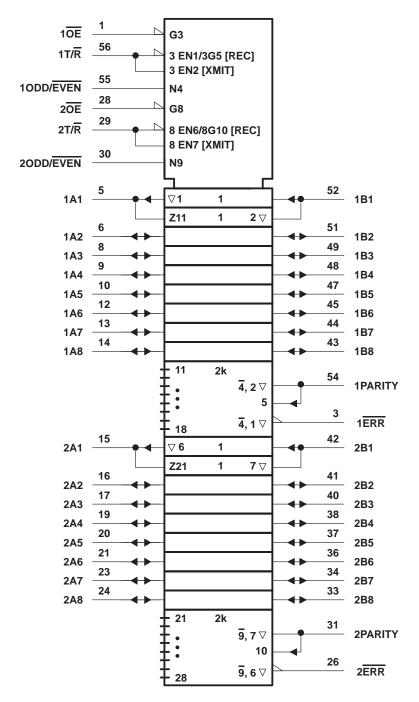
The SN54ABT16657 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16657 is characterized for operation from –40°C to 85°C.

## FUNCTION TABLE (each 8-bit section)

NUMBER OF A OR B		INPU	JTS	INPUT/OUTPUT		OUTPUTS
INPUTS THAT ARE HIGH	OE	E T/R ODD/EVEN		PARITY	ERR	OUTPUT MODE
	L	Н	Н	Н	Z	Transmit
	L	Н	L	L	Z	Transmit
0.2460	L	L	Н	Н	Н	Receive
0, 2, 4, 6, 8	L	L	Н	L	L	Receive
	L	L	L	Н	L	Receive
	L	L	L	L	Н	Receive
	L	Н	Н	L	Z	Transmit
	L	Н	L	Н	Z	Transmit
4 2 5 7	L	L	Н	Н	L	Receive
1, 3, 5, 7	L	L	Н	L	Н	Receive
	L	L	L	Н	Н	Receive
	L	L	L	L	L	Receive
Don't care	Н	Χ	Х	Z	Z	Z



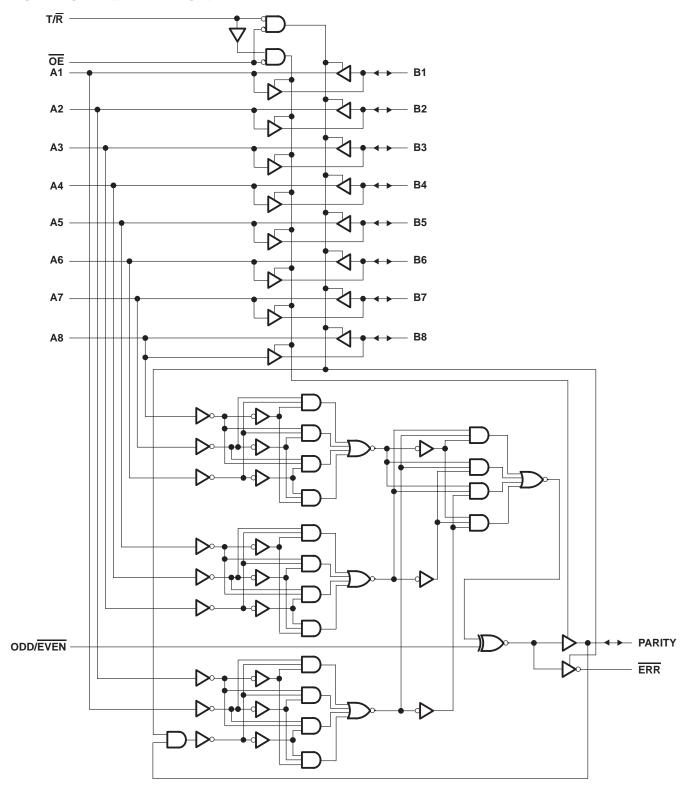
## logic symbol†



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

SCBS103B - FEBRUARY 1992 - REVISED JANUARY 1997

### logic diagram (positive logic)





SCBS103B - FEBRUARY 1992 - REVISED JANUARY 1997

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	
Input voltage range, V <sub>I</sub> (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	$-0.5~\textrm{V}$ to 5.5 $\textrm{V}$
Current into any output in the low state, IO: SN54ABT16657	96 mA
SN74ABT16657	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): DGG package	81°C/W
DL package	74°C/W
Storage temperature range, T <sub>sta</sub>	$-65^{\circ}$ C to $150^{\circ}$ C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 3)

			SN54ABT	16657	SN74AB1	16657	UNIT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	EM	2		V	
VIL	Low-level input voltage		0.8		0.8	V	
٧ <sub>I</sub>	Input voltage		0 0	VCC	0	VCC	V
loh	High-level output current		40,	-24		-32	mA
loL	Low-level output current	200	48		64	mA	
Δt/Δν	Input transition rise or fall rate	Outputs enabled	B	10		10	ns/V
TA	Operating free-air temperature		<b>–</b> 55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

SCBS103B - FEBRUARY 1992 - REVISED JANUARY 1997

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER TEST CONDITIONS		UDITIONS	Т	A = 25°C	;	SN54AB	Г16657	SN74AB1	Γ16657	UNIT	
Ρ/	ARAMETER	l lesi coi	NUTTIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		
\/a		$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$	3			3		3		V
VOH		V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -24 mA	2			2				V
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$	2*					2		
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 24 mA			0.55		0.55			V
VOL		VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$			0.55*				0.55	V
V <sub>hys</sub>					100			IFL			mV
	Control inputs	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = V <sub>CC</sub> or GND			±1		₹ ±1		±1	μА
Ħ	A or B ports	VCC = 5.5 V,	AL = ACC OLGIAD			±100	_ <	±100		±100	μΑ
IOZH	‡	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.7 \text{ V}$			50	S	50		50	μΑ
lozL <sup>2</sup>	‡	$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.5 V$			-50	9	-50		-50	μΑ
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$			±100	Q'	±450		±100	μΑ
ICEX		V <sub>C</sub> C = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ
ΙΟ§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA
		V <sub>CC</sub> = 5.5 V,	Outputs high			2		2		2	
ICC	A or B ports	$I_O = 0$ ,	Outputs low			36		36		36	mA
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2	
∆lcc'	¶	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND				50		50		50	μΑ
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			3						pF
Cio	A or B ports	V <sub>O</sub> = 2.5 V or 0.5 V			9						pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter does not apply.

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>&</sup>lt;sup>‡</sup> The parameters IOZH and IOZL include the input leakage current.

<sup>§</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>¶</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

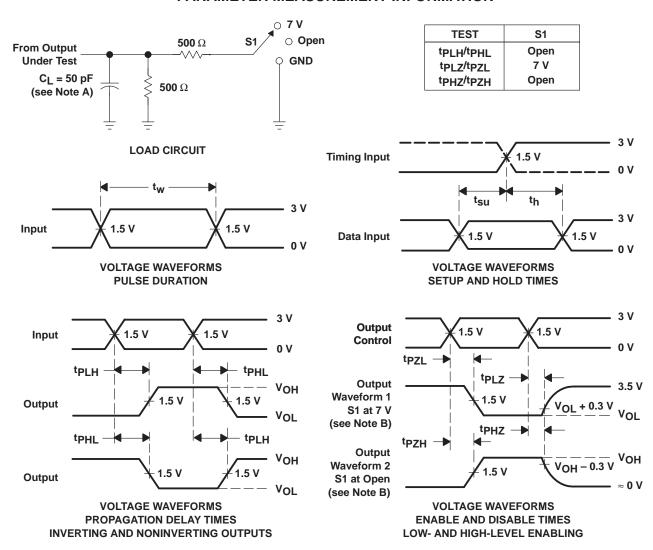
SCBS103B - FEBRUARY 1992 - REVISED JANUARY 1997

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>(</sub>	CC = 5 V 4 = 25°C	', ;	SN54AB	Г16657	SN74AB1	Г16657	UNIT	
	(INFOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
<sup>t</sup> PLH	A or B	B or A	1.5	2.5	3.3	1.5	4.2	1.5	4.1	ns	
<sup>t</sup> PHL	AUIB	BULA	2	3.1	3.9	2	4.5	2	4.3	115	
t <sub>PLH</sub>	А	PARITY	2	4.6	5.4	2	7	2	6.7	ns	
t <sub>PHL</sub>	A	PARITI	2	4.3	5.1	2	6.5	2	6.1	115	
<sup>t</sup> PLH	ODD/EVEN	DARITY FOR	2	4.6	5.4	2	7	2	6.7	ns	
t <sub>PHL</sub>	ODD/EVEN	PARITY, ERR	2	4.3	5.1	2	6.5	2	6.1	ris	
t <sub>PLH</sub>	В	ERR	2	4.6	5.4	2	7	2	6.7	ns	
t <sub>PHL</sub>	Ь	EKK	2	4.3	5.1	2	6.5	2	6.1	] "15	
<sup>t</sup> PLH	PARITY	ERR	2	4.6	5.4	2	7	2	6.7	ns	
<sup>t</sup> PHL	FANITI	EKK	2	4.3	5.1	2	6.5	2	6.1	115	
<sup>t</sup> PZH	<u>OE</u>	A or B	2	3.9	4.9	2 2	5.8	2	5.6	ns	
t <sub>PZL</sub>	OE	AOIB	2.5	4.3	5.1	2.5	6.2	2.5	6	115	
<sup>t</sup> PHZ	<u>OE</u>	A or B	2	3.6	4.5	2	5.5	2	5.4	ns	
t <sub>PLZ</sub>	OE	AOIB	1.5	3	3.8	1.5	4.7	1.5	4.3	115	
<sup>t</sup> PZH	ŌĒ	PARITY, ERR	2	4	4.9	2	5.8	2	5.6	ns	
<sup>t</sup> PZL	OE	PARII I, ERR	2.5	4.1	5.1	2.5	6.2	2.5	6	118	
<sup>t</sup> PHZ	ŌĒ	PARITY, ERR	1	3.5	4.5	1	5.5	1	5.4	ns	
t <sub>PLZ</sub>	OE .	FARILI, EKK	1.5	3	3.8	1.5	4.7	1.5	4.3	4.3	

SCBS103B - FEBRUARY 1992 - REVISED JANUARY 1997

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50~\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns,
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







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#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ABT16657DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABT16657DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16657DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16657DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16657DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16657DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16657DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

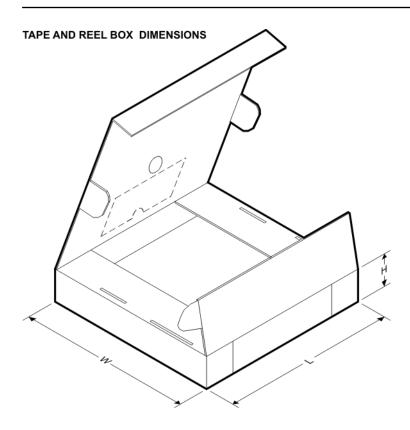
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT16657DGGR	TSSOP	DGG	56	2000	330.0	24.4	8.6	15.6	1.8	12.0	24.0	Q1
SN74ABT16657DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1





\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT16657DGGR	TSSOP	DGG	56	2000	346.0	346.0	41.0
SN74ABT16657DLR	SSOP	DL	56	1000	346.0	346.0	49.0

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